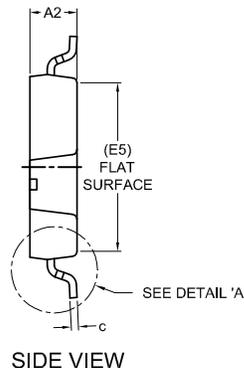
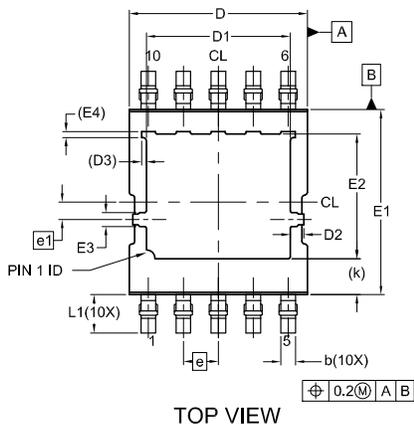


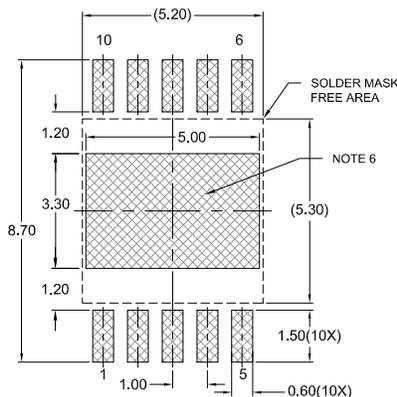
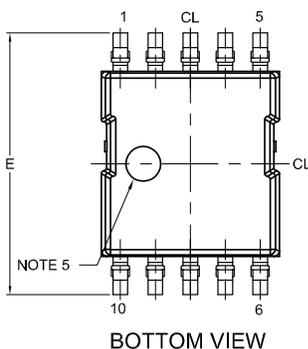


TCPAK10 5.1x7.5, 1.0P
CASE 760AG
ISSUE D

DATE 13 OCT 2022



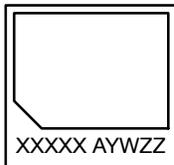
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. UNIT DIMENSION: MILLIMETERS
 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.150mm PER SIDE.
 4. DIMENSIONS D AND E1 ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
 5. OPTIONAL MOLD FEATURE.
 6. LAND PAD UNDER THE PACKAGE BODY IS FOR MECHANICAL SUPPORT ONLY. SOLDER CONNECTION IS NOT REQUIRED.
 7. DIMENSION A1 IS THE LEAD STAND-OFF FROM THE BOTTOM SURFACE OF THE PACKAGE BODY.



*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

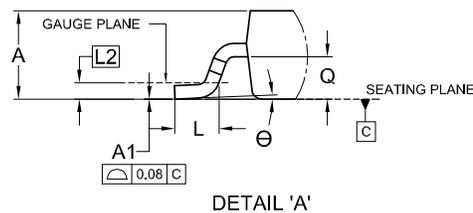
MILLIMETERS			
DIM	MIN	NOM	MAX
A	1.30	1.35	1.45
A1	-0.05	0.00	0.05
A2	1.30	1.35	1.40
b	0.36	0.41	0.46
c	0.16	0.21	0.26
D	5.00	5.10	5.20
D1	4.02	4.12	4.22
D2	0.30	0.40	0.50
D3	0.14 REF		
E	7.40	7.50	7.60
E1	5.20	5.30	5.40
E2	3.47	3.57	3.67
E3	0.30	0.40	0.50
E4	0.17 REF		
E5	4.82 REF		
e	1.00 BSC		
e1	0.50 BSC		
k	1.03 REF		
L	0.49	0.69	0.89
L1	0.90	1.10	1.30
L2	0.25 BSC		
Q	0.60	0.65	0.70
θ	0°	2.5°	5°

GENERIC MARKING DIAGRAM*



- XXXX = Specific Device Code
- A = Assembly Location
- Y = Year
- W = Work Week
- ZZ = Assembly Lot Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "μ", may or may not be present. Some products may not follow the Generic Marking.



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